and the resulting product can be greatly minimized.

In the future, cooperation and communication among paper mill individuals; equipment suppliers; manufacturers of inks, coatings, and adhesives; and chemical suppliers can greatly benefit everyone. The goal should be to formulate inks, coatings, and adhesives so that they are effective and economical, and, at the same time, to allow current technology to be used without undue difficulty when waste papers are recycled.

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